

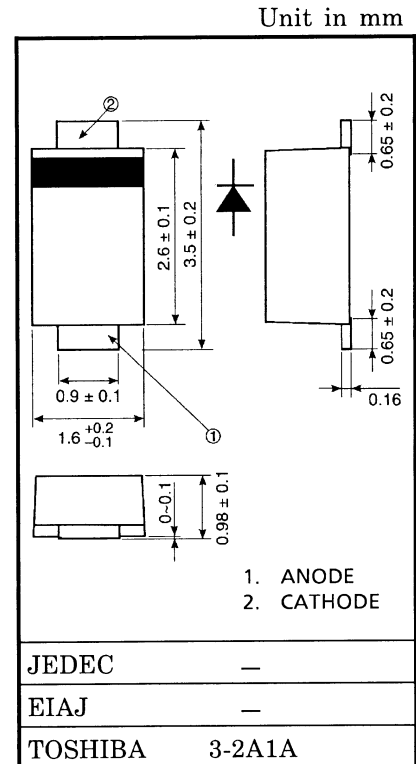
CRS08

Switching Type Power Supply Applications
 Portable Equipment Battery Applications

- Forward voltage: $V_{FM} = 0.36 \text{ V (max)}$
- Average forward current: $I_F (AV) = 1.5 \text{ A}$
- Repetitive peak reverse voltage: $V_{RRM} = 30 \text{ V}$
- Small package: "S-FLAT™" (Toshiba designation)

Maximum Ratings ($T_a = 25^\circ\text{C}$)

Characteristics	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	30	V
Average forward current	$I_F (AV)$	1.5	A
Peak one cycle surge forward current (non-repetitive)	I_{FSM}	30 (50 Hz)	A
Junction temperature	T_j	-40~125	$^\circ\text{C}$
Storage temperature	T_{stg}	-40~150	$^\circ\text{C}$



Weight : 0.013g

Electrical Characteristics ($T_a = 25^\circ\text{C}$)

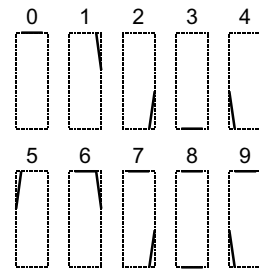
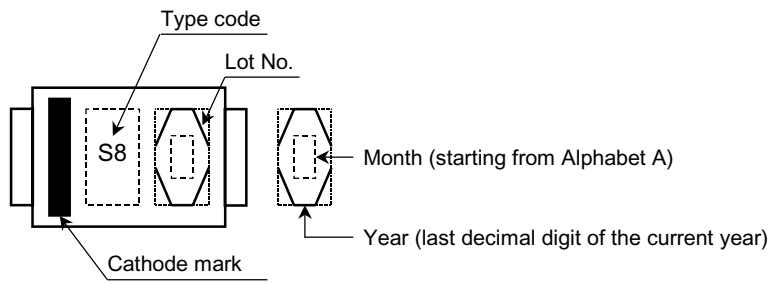
Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Peak forward voltage	$V_{FM} (1)$	$I_{FM} = 0.1 \text{ A}$	—	0.23	—	V
	$V_{FM} (2)$	$I_{FM} = 1.0 \text{ A}$	—	0.32	—	
	$V_{FM} (3)$	$I_{FM} = 1.5 \text{ A}$	—	0.345	0.36	
Repetitive peak reverse current	$I_{RRM} (1)$	$V_{RRM} = 5 \text{ V}$	—	50	—	μA
	$I_{RRM} (2)$	$V_{RRM} = 30 \text{ V}$	—	—	1.0	mA
Junction capacitance	C_j	$V_R = 10 \text{ V}, f = 1.0 \text{ MHz}$	—	90	—	pF
Thermal resistance	$R_{th} (j-a)$	On ceramic substrate (soldering land 2 mm × 2 mm)	—	—	70	$^\circ\text{C/W}$
		On glass-epoxy substrate (soldering land 6 mm × 6 mm)	—	—	140	

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Marking

Following Indicates the Date of Manufacture



Standard Soldering Pad

